Material Features:

- Low pressure capabilities
- Low thermal resistance
- Good thermal stability

Applications

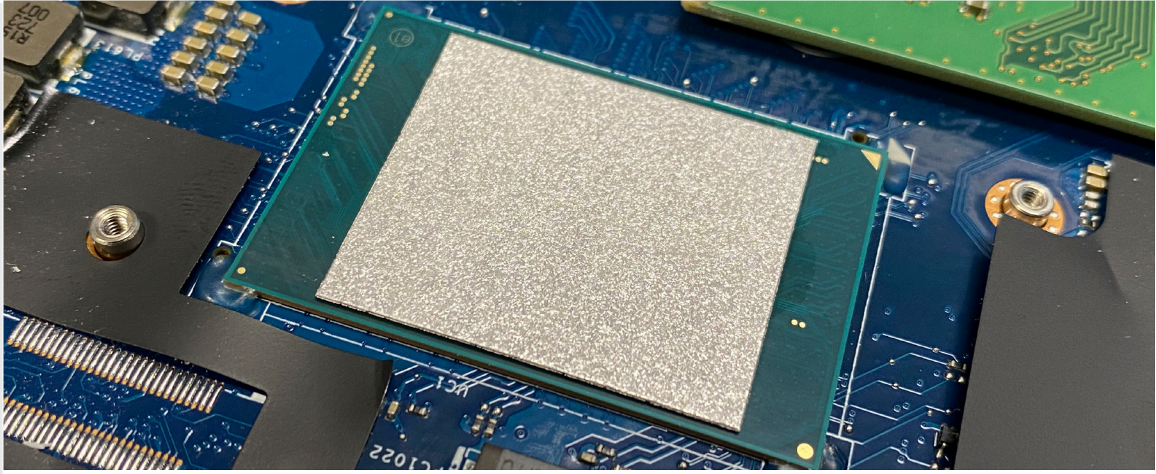
- Graphic Processors
- Base stations
- Microprocessors
- Laptops, CPU/APUs

Storage Conditions:

- Store in dark environment
- Storage Temperature: ≤ 30 ℃
- Storage Humidity: ≤ 70%

Shelf Life:

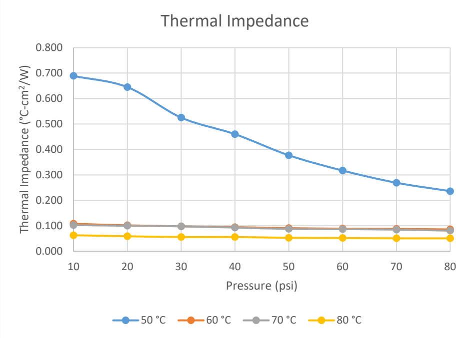
- Stored at storage conditions: one year



TCI Series

Leader Tech's TCI series is a new type of composite indium sheet capable of transitioning from solid to liquid at its melting point and back to solid again at room temperature. Capable of uniform thermal resistance at compressed environments where low stress is applied.

Part Series	Test Method	TCI800
Thermal Properties		
Thermal Conductivity Z axis (W/m-K)	ASTM D 5470	≥ 80
Thermal Conductivity X axis (W/m-K), Y axis (W/m-K)	ASTM D 5470	80
Thermal Impedance (°C-cm^2/W; @50psi)	ASTM D 5470	≤ 0.04
Physical Properties		
Color	Visual	Bright Silver
Thickness Range (in, (mm))	ASTM D 374	0.008-0.020 (0.2-0.5)
Width & Length (in, (mm))	N/A	5.91 x 5.91 (150 x 150)
Density (lb/in^3, (g/cc))	ASTM D 792	0.264 (7.3)
Operating Temperature (°F (°C))	IEC60068-2-14	-58 to 932 (-50 to 500)
Melting Point (°F (°C))	GB/T6 1425-1996	176 (80)
Electrical Resistivity (ohm-m)	GB/T6 146-2010	8.4 x 10-8
Shelf Life (Months)	N/A	12
Compressive Stress % (@50psi)	ASTM D 575	20



Samples size:25.4mm*25.4mm,Thickness:0.25mm

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